

This listing of claims will replace all prior versions, and listings, of claims in this patent application.

**Listing of Claims:**

1.-16. (Canceled)

17. (Currently amended) An electrotransport device comprising:

a non-conductive ~~reservoir~~ housing for the reservoir of the electrotransport device that comprising comprises a substantially flexible electrically conductive element integrally molded within the non-conductive housing,

wherein a first portion of the conductive element is within the reservoir housing and a second portion of the element is disposed on the outside of the reservoir housing and extends therefrom,

and wherein a substantially liquid and moisture-impermeable bond is created between the material forming the reservoir housing and the conductive element.

18. (Previously Presented) The electrotransport device of claim 17, wherein the reservoir housing is a single integral component.

19. (Previously Presented) The electrotransport device of claim 18, wherein the electrotransport device is manufactured without the fabrication of openings or other passages through the reservoir housing.

20. (Previously Presented) The electrotransport device of claim 17, wherein the conductive element comprises a substantially planar member.

21. (Previously Presented) The electrotransport device of claim 17, wherein the conductive element includes a base member having a conductive coating disposed thereon.